



PK596 (v1.0) February 15, 2013

# 100% Material Declaration Data Sheet for 7 Series CLG400 Package

**Average Weight: 0.9090 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.025878</b>	<b>2.847</b>
	Silicon	7440-21-3	100.00		0.025878	
<b>Die Attach Material</b>					<b>0.008105</b>	<b>0.892</b>
	Silver	7440-22-4	77.50		0.006281	
	Bismaleimide monomer	Trade Secret	15.00		0.001216	
	Acrylate monomer	Trade Secret	7.50		0.000608	
<b>Mold Compound</b>					<b>0.376323</b>	<b>41.400</b>
	Epoxy Resin	Trade secret	5.00		0.018816	
	Phenol Resin	Trade secret	3.00		0.011290	
	Phenol Novolac	9003-35-4	3.00		0.011290	
	Metal Hydroxide	Trade Secret	3.00		0.011290	
	Carbon black	1333-86-4	0.30		0.001129	
	Silica fused	60676-86-0	70.40		0.264931	
	Silica Dioxide	7631-86-9	15.00		0.056448	
	Silica, crystalline	14808-60-7	0.30		0.001129	
<b>Copper Wire</b>					<b>0.005401</b>	<b>0.594</b>
	Copper	7440-50-8	98.20		0.005304	
	Palladium	7440-05-3	1.80		0.000097	
<b>Solder Ball</b>					<b>0.193372</b>	<b>21.273</b>
	Tin	7440-31-5	96.50		0.186604	
	Silver	7440-22-4	3.00		0.005801	
	Copper	7440-50-8	0.50		0.000967	
<b>Substrate</b>					<b>0.299922</b>	<b>32.995</b>
	Gold	7440-57-5	0.18		0.000540	
	Nickel	7440-02-0	1.63		0.004889	
	Copper	7440-50-8	43.97		0.131876	
	Glass Fiber	65997-17-3	21.29		0.063853	
	Non halogen fire retardant	Trade Secret	0.01		0.000030	
	BT core	105391-33-1 25722-66-1 Trade Secret	26.01		0.078010	
	Solder Mask	34590-94-8 7727-43-7 Trade Secret	6.90		0.020695	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/15/2013	1.0	Xilinx Initial Release

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